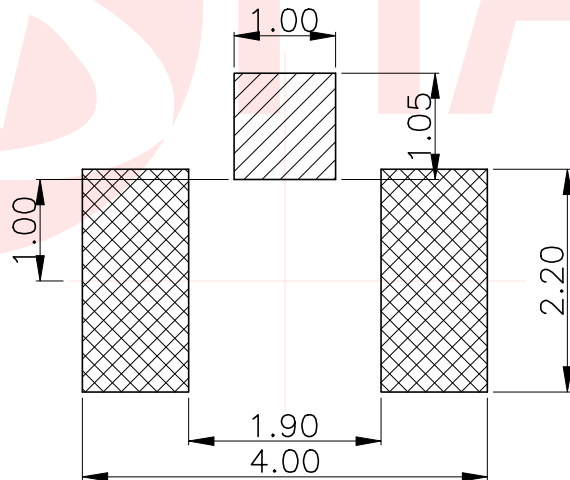
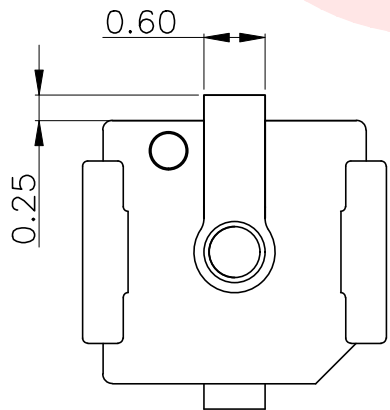
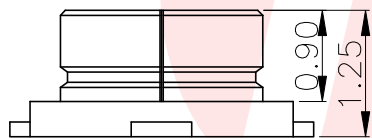
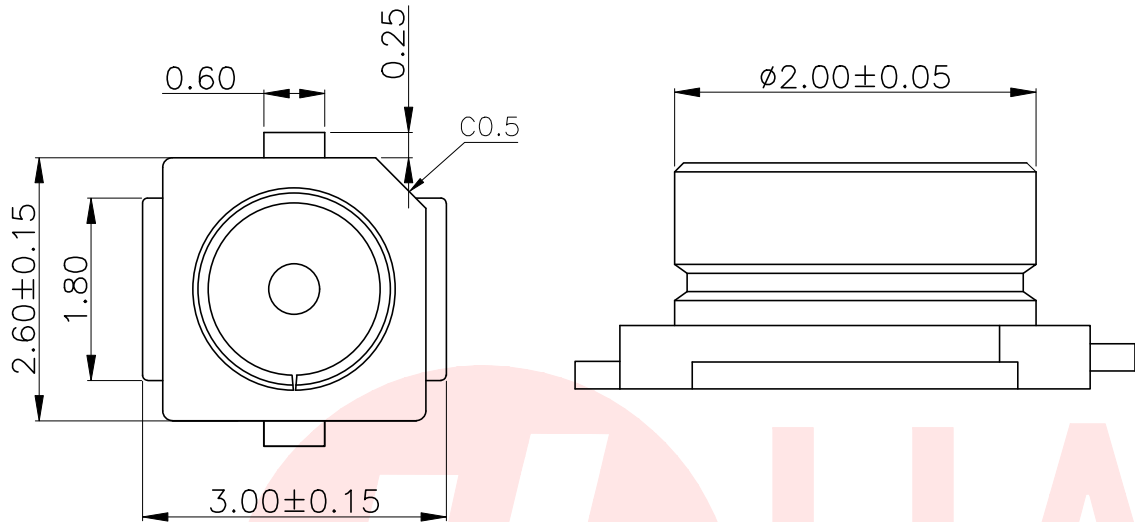


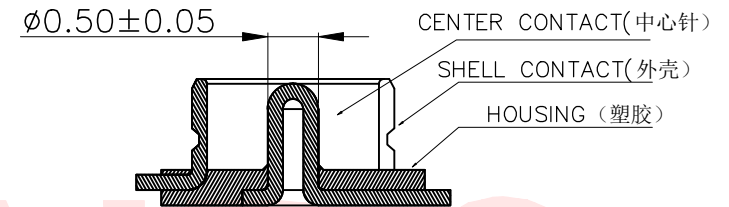


REV.	ECN NO OR DESCRIPTION	REVISED	DATE



RECOMMENDED PCB LAYOUT
(TOLERANCE: ±0.05)

 CENTER CONTACT  GROUND CONTACT



NOTES(备注) :

- 1.0. RATING(额定值) :
 - 1.1. VOLTAGE(电压) : 60 VAC (R.M.S.)
 - 1.2. NOMINAL CHARACTERISTIC IMPEDANCE(特性阻抗): 50 Ohm
 - 1.3. APPLICABLE FREQUENCY(适用频率): DC ~ 6GHz
 - 1.4. VSWR(电压驻波比): 1.3 MAX. (DC~3GHz), 1.5 MAX. (3~6GHz)
 - 1.5. TEMPERATURE(适用温度) : -40°C TO +85°C
 - 1.6. APPLIED TO IR SOLDERING PROCESS(适用回流焊接方式)
- 2.0. MATERIAL SEE BILL OF MATERIAL (材料清单):
 - 2.1. HOUSING(塑胶): THERMOPLASTIC LCP, UL94V-0 (LCP符合UL94V-0),
 - 2.2. CENTER CONTACT(中心端子) : COPPER ALLOY C5191(铜合金C5191).
 - 2.3. SHELL CONTACT(外壳): COPPER ALLOY C5191(铜合金C5191).

UNLESS OTHERWISE SPECIFIED TOLERANCES		 东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS: ANGLES:		TITLE MICRO RF BOARD SMT 3 PADS TYPE			
X : ±0.35	X : ±2°	DWN	xiong	PART NO. SP-IPEX-001S	
X.X : ±0.25	X.X : ±1°	CHKD	lee	SCALE: 1:1	UNIT: mm
X.XX : ±0.15		APVD	wang	SIZE: A4	SHEET: 10F 1
		REV: A4			
		CUSTOMER COPY			